

BOARD ON CHIP BALL GRID ARRAY(BOC-BGA)
ABSTRACT OF THE DISCLOSURE:

A package for an integrated circuit includes a circuit board 122 for mounting the integrated circuit 114 having a first surface and a second surface, a connection device positioned on the first surface of the circuit board 122 for electrically connecting the integrated circuit 114 and the integrated circuit 114 being positioned on the second surface of the integrated circuit 114.

Figure 1